



# Our Products

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## Perfluoropolyethers (PFPEs) Dielectric Fluid Solutions

Electronics Testing  
 Vapor Phase Reflow  
 Liquid Immersion Cooling  
 Custom Applications



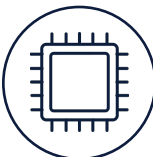
## Test & Inspection Solutions

Burn-In and Test Sockets  
 Burn-In and Test Printed Circuit Board  
 Bond Testing (Wire, Die)  
 Wafer Level 2D/3D AOI  
 Surface Metrology  
 Wafer Level X-Ray Inspection  
 Package Level 2D/3D AOI  
 Package Level 2D/3D X-Ray Inspection  
 Acoustic Micro Imaging (AMI)



## Materials

Bonding Wire  
 Die Attach Material  
 PFPE Solvents  
 PVDF Thermoplastics



## Metalized & Ceramic Packages

Metalized & Ceramic Lids  
 Hermetic Parts  
 Lead Frames (Etch, Rolled)  
 Solder Preforms  
 Carrier & Ceramics



## Facilities Closed Loop DI Water

Waste Water Treatment  
 DI Water Resin  
 Chilled Water Control  
 Metals Elimination & Water Recycling



## Equipment Tooling

Wire Bonders (Fine/Heavy Wire, Ribbon, Tab)  
 Die Bonders (Die Collets)  
 Die Sorters (Pick-up Tooling)  
 Fluid Dispensers (Nozzles)  
 Wafer/Thin Film Probers (Four Point Probes)  
 Solder Jet Balling  
 Clip Bond Dispenser



## Wafer Packaging & Assembly Equipment

Grinders, Dicing Saws & Laser Singulation/Grooving  
 Die Sorters/Pick & Place



## Wafer Process & Lamination Tools

Photopolymer Film Lamination  
 DIE Attach Film Lamination  
 Dry Metal Lift Off  
 BG & Temporary Bonding Film Lamination



## Advanced Packaging Solutions

Pressurized Ag Sintering  
 Advanced Transfer Molding  
 Laser Selective Solder Reflow



## Services

Wafer Processing  
 • Dicing  
 • Grinding  
 • Stealth Dicing  
 • Laser Grooving

Wafer AOI  
 Wafer Metrology  
 Die Attach Package Development  
 Transfer Molding Package  
 Wire Bonder Parts & Repair

